

## Schottky Barrier Diode DB2J41100L

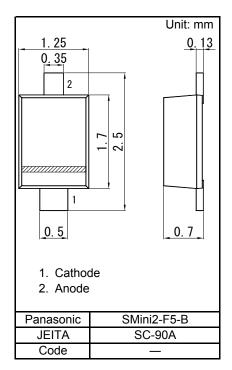
### DB2J41100L Silicon epitaxial planar type

#### For rectification

- Features
- · Low forward voltage and low reverse leakage current
- Short reverse recovery time trr
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 4R

Packaging

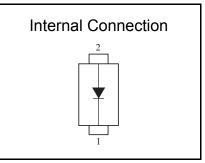
Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



#### Absolute Maximum Ratings Ta = 25 °C Parameter Symbol Rating Unit Reverse voltage VR 40 V Forward current (average) IF(AV) 1 А Non-repetitive peak forward surge current IFSM 3 А 125 °C Junction temperature Tj °C Operating ambient temperature Topr -40 to +85 -55 to +125 °C Storage temperature Tstg

Note: \*1 For embedded alumina substrate (substrate size: 5 cm× 5 cm)

\*2 50 Hz sine wave 1 cycle (Non-repetitive peak current)



## **Panasonic**

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#### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 1 A		0.50	0.58	V
Reverse current	IR	VR = 40 V		15	100	μA
Terminal capacitance	Ct	VR = 10 V, f = 1 MHz		21		pF
Reverse recovery time <sup>*1</sup>	trr	IF = 100 mA, Irr = $0.1 \times IR$ , RL = 100 $\Omega$		6.8		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

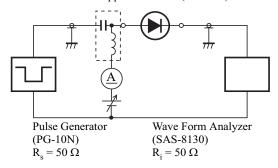
This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

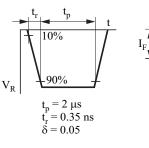
3. \*1 trr test circuit

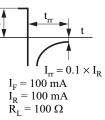
Bias Application Unit (N-50BU)

Input Pulse

Output Pulse



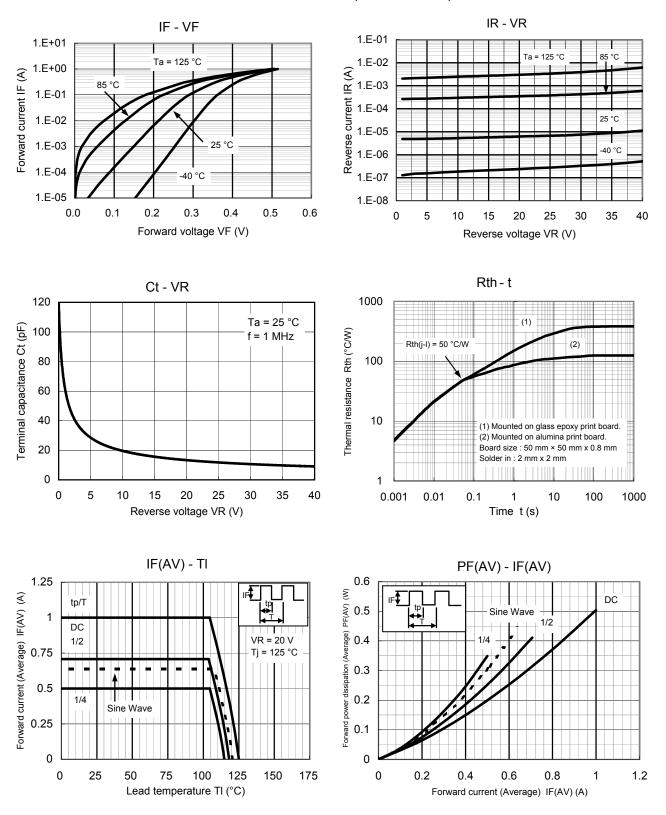




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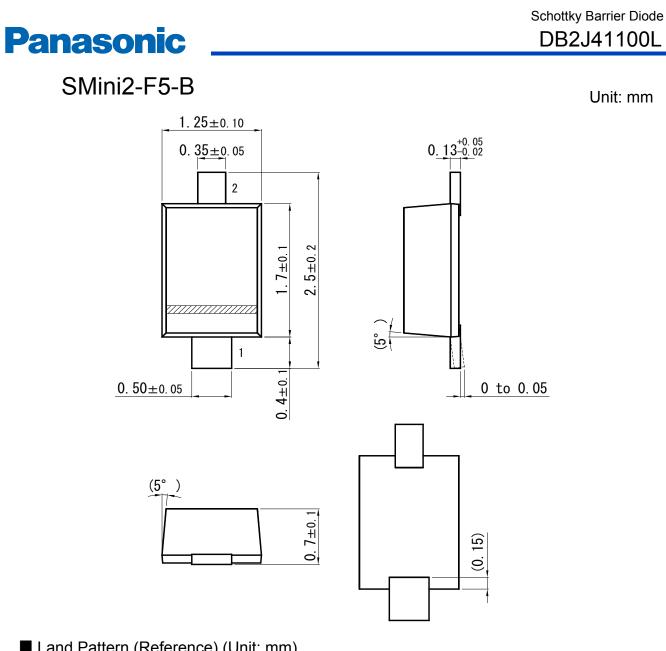


Technical Data (reference)

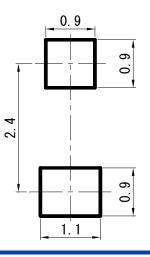


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Established : 2009-10-09 Revised : 2013-04-20



Land Pattern (Reference) (Unit: mm)



Established : 2009-10-09 Revised : 2013-04-20

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